

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Cancelled)

2. (Cancelled)

3. (Cancelled)

4. (Currently amended) An electronic circuit[,] comprising:

an electronic substrate made from a porous material into which a fluid material permeates, the fluid material including a material for formation of a circuit pattern, according to Claim 1, and

a circuit pattern which is formed by said liquid material permeating into said electronic substrate and solidifying,

wherein said liquid material comprises at least one of a conductive material, a semiconducting material, an insulating material, and a dielectric material as said material for formation of the circuit pattern, and

wherein said circuit pattern includes an active element which is formed from said material for formation of the circuit pattern.

5. (Cancelled)

6. (Currently amended) An electronic circuit according to claim ~~5~~4, wherein said circuit pattern includes a condenser which is formed from said material for circuit pattern formation.

7. (Currently amended) An electronic circuit according to claim ~~5~~4, wherein said circuit pattern includes an inductance which is formed from said material for circuit pattern formation.

8. (Currently amended) An electronic circuit according to claim ~~5~~4, wherein said circuit pattern includes a resistor which is formed from said material for circuit pattern formation.

9. (Currently amended) An electronic circuit according to claim ~~5~~4, wherein said circuit pattern includes a lead wire or an electrode which is formed from said material for circuit pattern formation.

10. (Cancelled)

11. (Cancelled)

12. (Cancelled)

13. (New) An electronic circuit according to claim 4, wherein a main component of said porous material is a ceramic.

14. (New) An electronic circuit according to claim 4, wherein a main component of said porous material is a fiber material.

15. (New) An electronic circuit according to claim 4, wherein said liquid material includes at least one of the conductive material and the semiconductive material as said material for formation of the circuit pattern and exhibits a characteristic of non-affinity with respect to said liquid material including at least one of the insulating material and the dielectric material as said material for formation of the circuit pattern.